RENESAS

HZM6.8ZMFA

Silicon Planar Zener Diode for Surge Absorb

REJ03G1211-0300 (Previous: ADE-208-783B) Rev.3.00 Jun 14, 2005

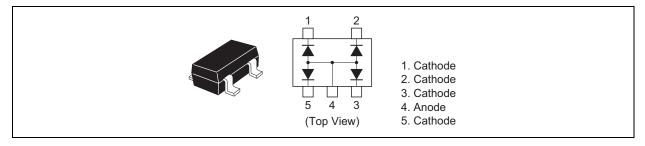
Features

- HZM6.8ZMFA has four devices in a monolithic, and can absorb surge.
- Low capacitance (C = 25 pF max) and can protect ESD of signal line.
- MPAK-5 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HZM6.8ZMFA	68N	MPAK-5	PLSP0005ZC-A (MPAK-5)

Pin Arrangement





Absolute Maximum Ratings

(Ta = 25°C)

Symbol	Value	Unit
Pd *	200	mW
Tj	150	°C
Tstg	-55 to +150	°C
	Pd * Tj	Pd * 200 Tj 150

Note: Four device total, See Fig.2.

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

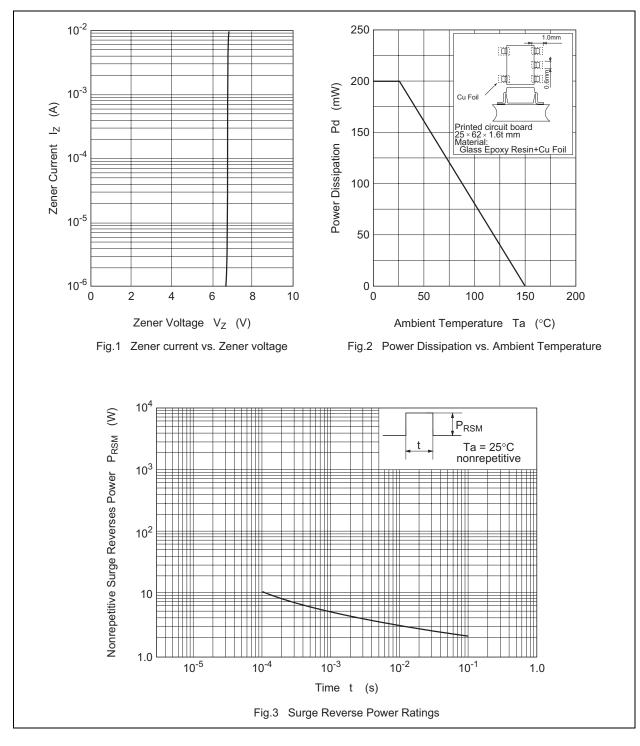
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	6.47	_	7.00	V	I _Z = 5 mA, 40 ms pulse
Reverse current	I _R	_	_	2	μA	V _R = 3.5 V
Capacitance	С	_	_	25	pF	V _R =0 V, f = 1 MHz
Dynamic resistance	r _d	_	_	30	Ω	I _Z = 5 mA
ESD-Capability * ²	_	25	_	—	kV	C = 150 pF, R = 330 Ω , Both forward and reverse direction 10 pulse.

Notes: 1. Per one device

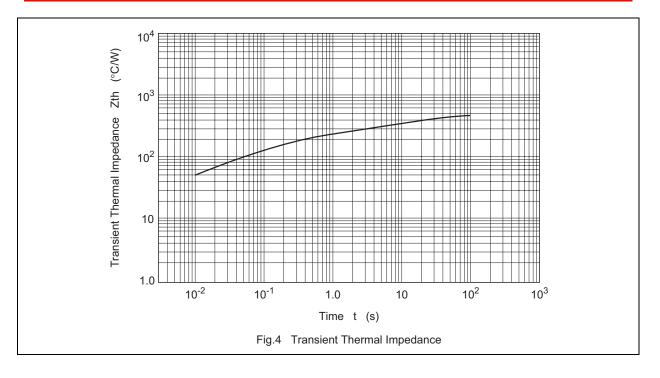
2. Failure criterion ; $I_R>2~\mu A$ at V_R = 3.5 V.



Main Characteristic

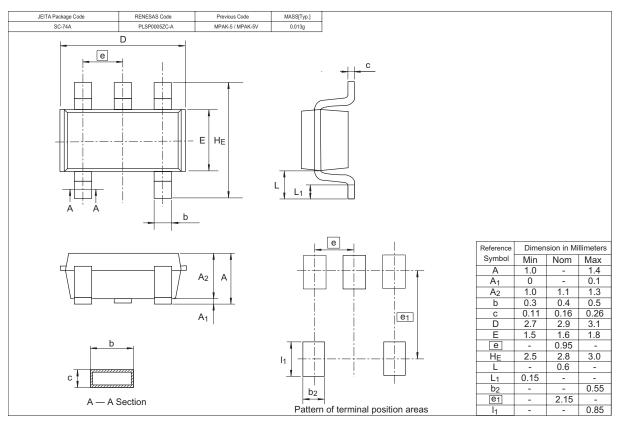








Package Dimensions





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